Functional Safety Information

INA301-Q1 Functional Safety, FIT Rate, Failure Mode Distribution and Pin FMA

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Trademarks

1 Overview

This document contains information for the INA301-Q1 (in VSSOP-8 package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device

Figure 1-1 shows the device functional block diagram for reference.

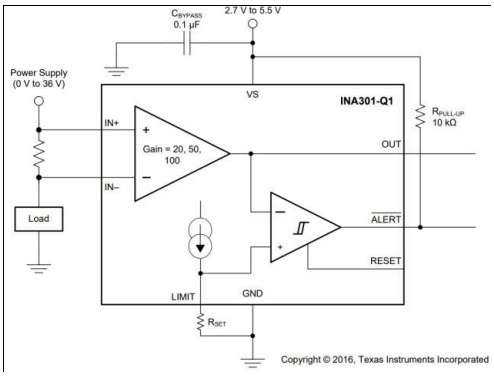

Figure 1-1. Functional Block Diagram

The INA301-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for the INA301-Q1 based on two different industry-wide used reliability standards:

- Table 2-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 2-2 provides FIT rates based on the Siemens Norm SN 29500-2

Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10^9 Hours)
Total Component FIT Rate	7
Die FIT Rate	3
Package FIT Rate	4

The failure rate and mission profile information in Table 2-1 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 55 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T_J
4	BICMOS Op Amp, Comparators, Voltage Monitors	8 FIT	45°C

The Reference FIT Rate and Reference Virtual T_J (junction temperature) in Table 2-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for the INA301-Q1 in Table 3-1 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 3-1. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
VOUT open (Hi-Z)	10%
VOUT Stuck (High/Low)	25%
VOUT functional, not in specification	30%
ALERT false trip, failure to trip	35%

4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the INA301-Q1. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to Supply (see Table 4-5)

Table 4-2 through Table 4-5 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 4-1.

Table 4-1. TI Classification of Failure Effects

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

Figure 4-1 shows the INA301-Q1 pin diagram. For a detailed description of the device pins please refer to the *Pin Configuration and Functions* section in the INA301-Q1 data sheet.

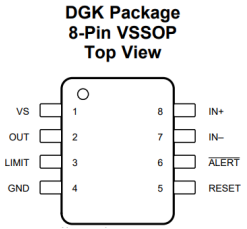

Figure 4-1. Pin Diagram

Following are the assumptions of use and the device configuration assumed for the pin FMA in this section:

- T_A = -40°C to +125°C
- V_S = 5 V
- V_{IN+} = 12 V
- REF = V_S/2.

Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VS	1	Power supply shorted to ground.	B
OUT	2	Output shorts to ground. When left in this configuration for a long time, under high supplies self heating could cause dice junction temperature to exceed 150 degrees Celsius.	B
LIMIT	3	$\overline{\text{ALERT}}$ output is stuck low.	B
GND	4	Normal Operation.	D
RESET	5	If intended connection is not GND, functionality will be affected.	D if RESET=GND by design; C otherwise
$\overline{\text{ALERT}}$	6	$\overline{\text{ALERT}}$ output is stuck low.	B
IN_-	7	In high-side configuration, a short from the bus supply to GND will occur. High current will flow from bus supply to ground. In low-side configuration, normal operation.	B for high-side or D for low-side
IN_+	8	In high-side configuration, a short from the bus supply to GND will occur. High current will flow from bus supply to ground. In low side configuration, input pins are shorted.	B

Table 4-3. Pin FMA for Device Pins Open-Circuited

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VS	1	No power supply to device. Device may be biased through inputs. Output will be close to GND.	B
OUT	2	Output can be left open, there is no effect on the IC.	D
LIMIT	3	Comparator threshold is not defined.	B
GND	4	Output will be incorrect as it is no longer referenced to GND.	B
RESET	5	Comparator mode is not defined.	B
$\overline{\text{ALERT}}$	6	Pin can be left open if not needed.	D
IN_-	7	Differential input voltage is not well defined.	B
IN_+	8	Differential input voltage is not well defined.	B

Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
VS	1	OUT	Output shorts to supply. When left in this configuration for a long time, under high supplies self heating could cause dice junction temperature to exceed 150 degrees Celsius.	B
OUT	2	LIMIT	Comparator output will be unpredictable.	B
LIMIT	3	GND	$\overline{\text{ALERT}}$ output is stuck low.	B
GND	4	RESET	If intended connection is not GND, functionality will be affected.	D if RESET=GND by design; C otherwise
RESET	5	$\overline{\text{ALERT}}$	$\overline{\text{ALERT}}$ Comparator output will be unpredictable.	B
$\overline{\text{ALERT}}$	6	IN_-	In low-side configuration, ALERT output is stuck low; In high-side configuration, device damage is possible.	C for low-side; A for high-side
IN_-	7	IN_+	Input differential voltage=0V.	C
IN_+	8	VS	In high-side configuration, a short from the bus supply to VS will occur. High current will flow from bus supply to VS or vice versa. Device could be damaged.	A

Table 4-5. Pin FMA for Device Pins Short-Circuited to Supply

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VS	1	Normal operation.	D
OUT	2	Output shorts to supply. When left in this configuration for a long time, under high supplies self heating could cause dice junction temperature to exceed 150 degrees Celsius.	B
LIMIT	3	$\overline{\text{ALERT}}$ is stuck high or unpredictable.	B
GND	4	Power supply shorted to GND.	B
RESET	5	Comparator1 in Latch mode.	D if RESET=VS by design; C otherwise
$\overline{\text{ALERT}}$	6	$\overline{\text{ALERT}}$is stuck high. Power supply could be shorted to GND though this pin.	A
IN_-	7	In high-side configuration, a short from the bus supply to VS will occur. High current will flow from bus supply to VS or vice versa. Device could be damaged.	A for High side or B for low side
IN_+	8	In high-side configuration, a short from the bus supply to VS will occur. High current will flow from bus supply to VS or vice versa. Device could be damaged.	A for High side or B for low side

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